



Product Summary

Device	V _{(BR)DSS}	R _{DS(ON)}	I _D T _A = +25°C
Q1	12V	17mΩ @ V _{GS} = 4.5V	9.5A
QI	121	25mΩ @ V _{GS} = 2.5V	7.8A
02	-12V	32mΩ @ V _{GS} = -4.5V	-6.9A
Q2		53mΩ @ V _{GS} = -2.5V	-5.4A

Description and Applications

This new generation Complementary Pair Enhancement Mode MOSFET has been designed to minimize $R_{DS(on)}$ and yet maintain superior switching performance. This device is ideal for use in Notebook battery power management and Loadswitch.

- Notebook Battery Power Management
- DC-DC Converters
- Loadswitch

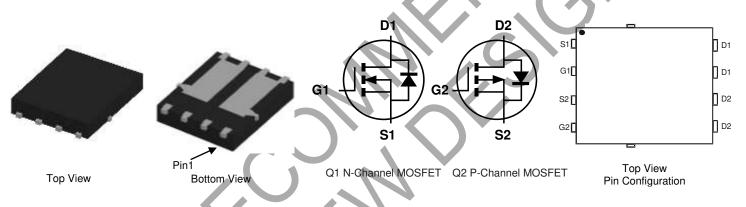
COMPLEMENTARY PAIR ENHANCEMENT MODE MOSFET POWERDI[®]5060-8

Features and Benefits

- Thermally Efficient Package-Cooler Running Applications
- High Conversion Efficiency
- Low R_{DS(ON)} Minimizes On State Losses
- Low Input Capacitance
- Fast Switching Speed
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: POWERDI5060-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram Below
- Weight: 0.097 grams (approximate)



Ordering Information (Note 4)

Part Number	Case	Packaging
DMC1017UPD-13	POWERDI5060-8	2500 / Tape & Reel

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant

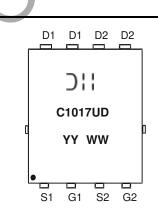
 See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information

Notes:



C1017UD = Product Type Marking C1017UD = Product Type Marking Code YYWW = Date Code Marking YY = Year (ex: 13 = 2013) WW = Week (01 - 53)



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteri	Symbol	Q1 Value	Q2 Value	Units		
Drain-Source Voltage	V _{DSS}	12	-12	V		
Gate-Source Voltage	V _{GSS}	±8	±8	V		
	Steady State	T _A = +25°C T _A = +70°C	ID	9.5 7.6	-6.9 -5.5	А
Continuous Drain Current (Note 5) $V_{GS} = 4.5V$	= 4.5V $T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$		ID	13.0 10.4	-9.4 -7.5	А
Maximum Body Diode Forward Current	ls	2	-2	А		
Pulsed Drain Current (10µs pulse, duty cycle = 1	I _{DM}	50	-35	А		
Avalanche Current (Note 6) L = 0.1mH	las	9.7	-9.2	А		
Avalanche Energy (Note 6) L = 0.1mH	E _{AS}	4.7	4.3	mJ		

Thermal Characteristics

Characteristic		Symbol	Value	Units
Total Power Dissipation (Note 5)	 = +25°C = +70°C	PD	2.3 1.5	W
Thermal Resistance, Junction to Ambient (Note 5)	eady state t<10s	R _{0JA}	54 29	°C/W
Thermal Resistance, Junction to Case (Note 5)		R _{ejc}	4.1	
Operating and Storage Temperature Range		Tj, Tstg	-55 to +150	°C
Operating and Storage Temperature Range		IJ, ISTG	-55 10 +150	

Electrical Characteristics Q1 N-Channel (@TA = +25°C, unless otherwise specified.)

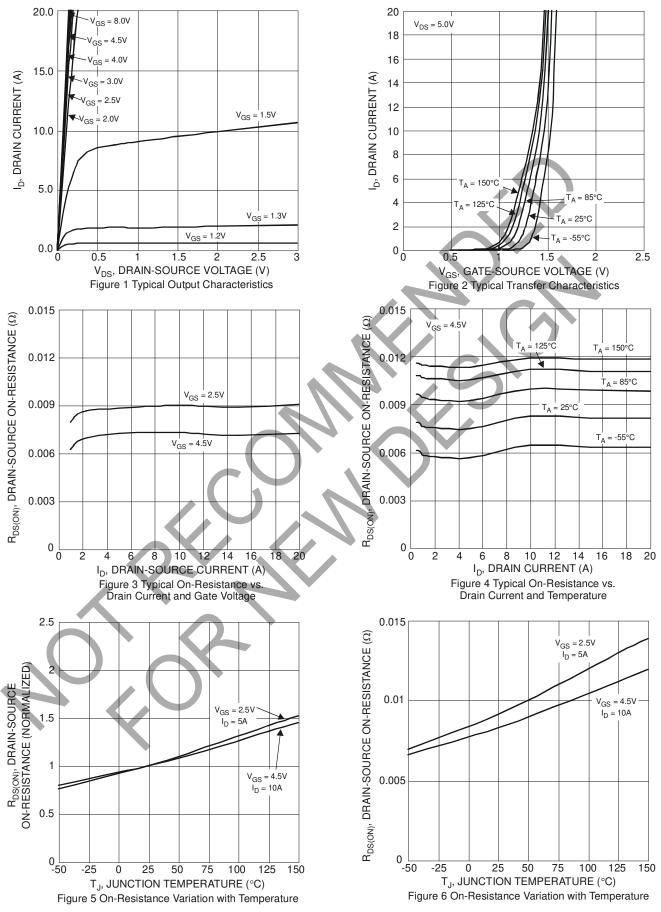
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)				V		
Drain-Source Breakdown Voltage	BV _{DSS}	12		_	V	$V_{GS} = 0V, I_D = 250\mu A$
Zero Gate Voltage Drain Current	IDSS			1	μA	$V_{DS} = 12V, V_{GS} = 0V$
Gate-Source Leakage	lgss		—	±100	nA	$V_{GS} = \pm 8V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 7)						·
Gate Threshold Voltage	V _{GS(th)}	0.6	_	1.5	V	$V_{DS} = V_{GS}, I_D = 250 \mu A$
Static Drain-Source On-Resistance			9.6	17	mΩ	$V_{GS} = 4.5V, I_D = 11.8A$
Static Drain-Source On-nesistance	R _{DS(ON)}		11	25	11152	$V_{GS} = 2.5V, I_D = 9.8A$
Diode Forward Voltage	VsD		0.7	1.2	V	V _{GS} = 0V, I _S = 2.9A
DYNAMIC CHARACTERISTICS (Note 8)			•			·
Input Capacitance	Ciss		1787	_	pF	$V_{DS} = 6V, V_{GS} = 0V,$ f = 1.0MHz
Output Capacitance	Coss	_	297			
Reverse Transfer Capacitance	Crss	_	265			
Gate Resistance	R _G		1.6		Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$
Total Gate Charge $(V_{GS} = 4.5V)$	Qg		18.6			
Total Gate Charge (V _{GS} = 10V)	Qg		35.4		nC	
Gate-Source Charge	Q _{gs}		2.7			$V_{DS} = 6V, I_D = 11.8A$
Gate-Drain Charge	Q _{gd}		3.8			
Turn-On Delay Time	t _{D(on)}		6.9			
Turn-On Rise Time	tr	_	10.9	_	nS	$\label{eq:VDD} \begin{split} V_{DD} &= 6V, \ R_L = 6\Omega \\ V_{GS} &= 4.5V, \ R_G = 6\Omega, \ I_D = 1A \end{split}$
Turn-Off Delay Time	t _{D(off)}		70.3		115	
Turn-Off Fall Time	t _f		31.8	_		
Body Diode Reverse Recovery Time	t _{rr}	—	13.1	_	nS	I _F = 11.8A, di/dt = 100A/µs
Body Diode Reverse Recovery Charge	Q _{rr}	_	2.2	_	nC	I _F = 11.8A, di/dt = 100A/μs

Notes:

5. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.

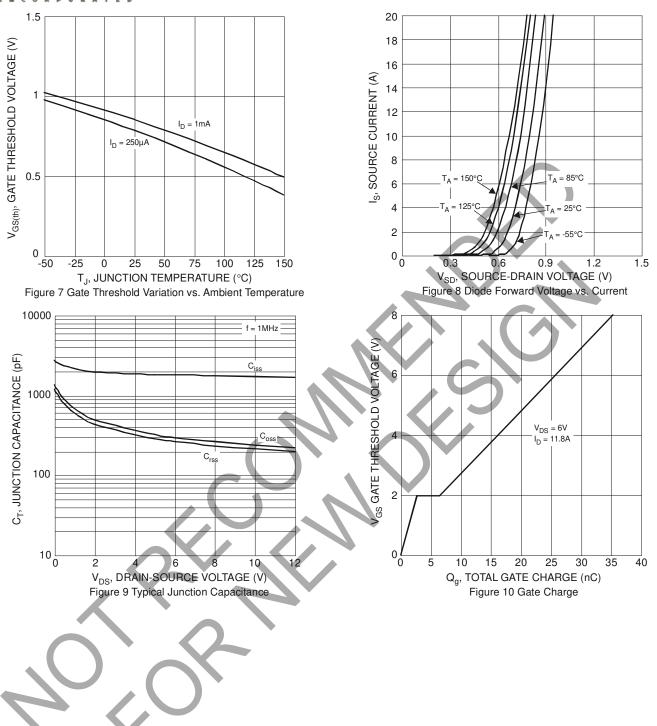
5. Device influence of the substate 10 board, 202 copper, with the square copper, $T_{J} = 25^{\circ}$ C. 7. Short duration pulse test used to minimize self-heating effect. 8. Guaranteed by design. Not subject to product testing.





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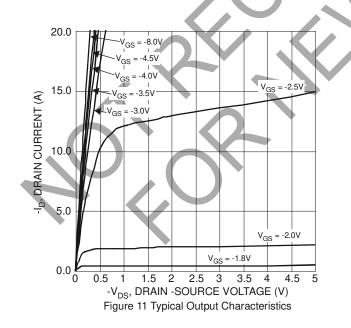


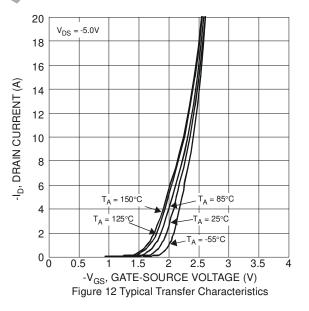


Electrical Characteristics Q2 P-Channel (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 6)	-,					
Drain-Source Breakdown Voltage	BV _{DSS}	-12	_	_	V	V _{GS} = 0V, I _D = -250µA
Zero Gate Voltage Drain Current	IDSS		_	-1	μA	$V_{DS} = -12V, V_{GS} = 0V$
Gate-Source Leakage	IGSS		_	±100	nA	$V_{GS} = \pm 8V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 6)				•		
Gate Threshold Voltage	V _{GS(th)}	-0.6	_	-1.5	V	$V_{DS} = V_{GS}, I_D = -250 \mu A$
Static Drain-Source On-Resistance	р		21	32	mΩ	$V_{GS} = -4.5V, I_D = -8.9A$
Static Drain-Source On-Resistance	R _{DS(ON)}		41	53	11122	$V_{GS} = -2.5V, I_D = -6.9A$
Diode Forward Voltage	V _{SD}	_	-0.7	-1.2	V	$V_{GS} = 0V, I_{S} = -2.9A$
DYNAMIC CHARACTERISTICS (Note 7)						
Input Capacitance	C _{iss}		2100			
Output Capacitance	Coss		872	_	pF	$V_{DS} = -6V$, $V_{GS} = 0V$, f = 1.0MHz
Reverse Transfer Capacitance	C _{rss}		626	-		1 - 1.00012
Gate Resistance	R _G		23.1		Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$
Total Gate Charge (V _{GS} = -4.5V)	Qg		23.7			
Total Gate Charge (V _{GS} = -8V)	Qg		38.8		nC	V _{DS} = -6V, I _D = -8.9A
Gate-Source Charge	Q _{gs}	_	5.3			$v_{DS} = -6v, I_D = -6.9A$
Gate-Drain Charge	Q _{gd}	_	9.8			
Turn-On Delay Time	t _{D(on)}		10.6	· -		
Turn-On Rise Time	tr		25.5		nS	$V_{DD} = -6V, R_L = 6\Omega$
Turn-Off Delay Time	t _{D(off)}		144			$V_{GS} = -4.5V, R_G = 6\Omega, I_D = -1A$
Turn-Off Fall Time	t _f		129			
Body Diode Reverse Recovery Time	trr		48.9		nS	I _F = -8.9A, di/dt = -100A/µs
Body Diode Reverse Recovery Charge	Q _{rr}]	15.3	_	nC	I _F = -8.9A, di/dt = -100A/μs

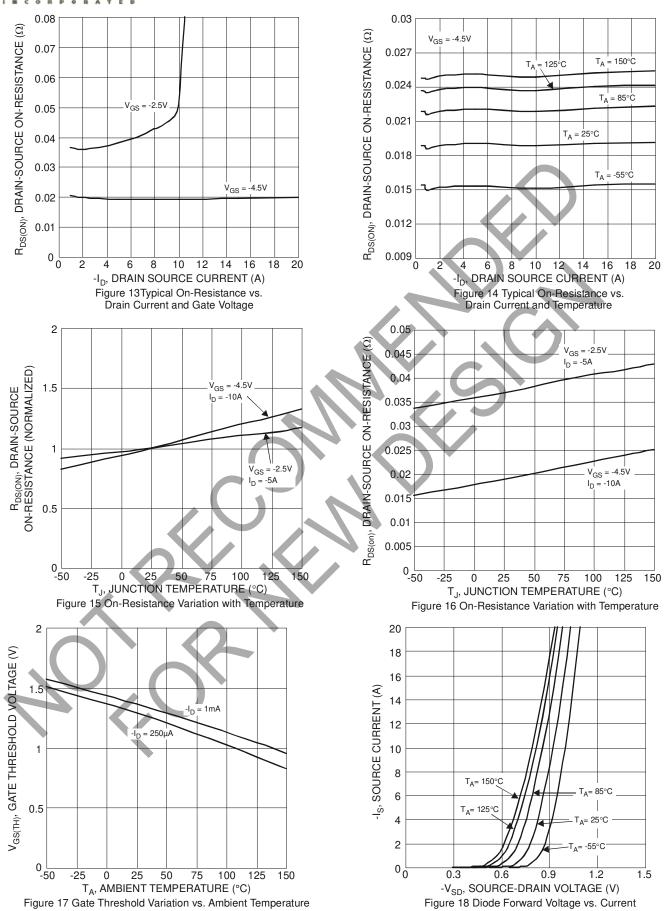
Notes: 6. I_{AS} and E_{AS} rating are based on low frequency and duty cycles to keep $T_J = 25^{\circ}$ C. 7. Short duration pulse test used to minimize self-heating effect.





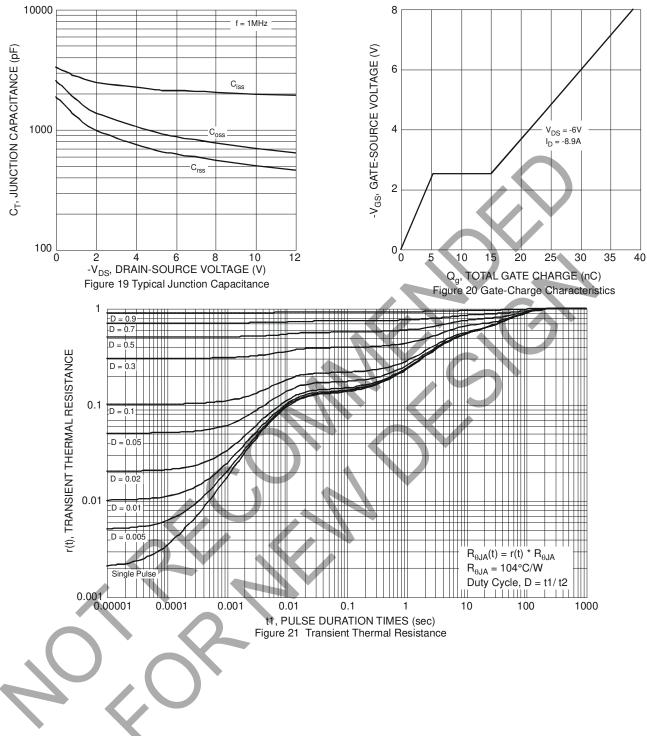
DECDES

DMC1017UPD



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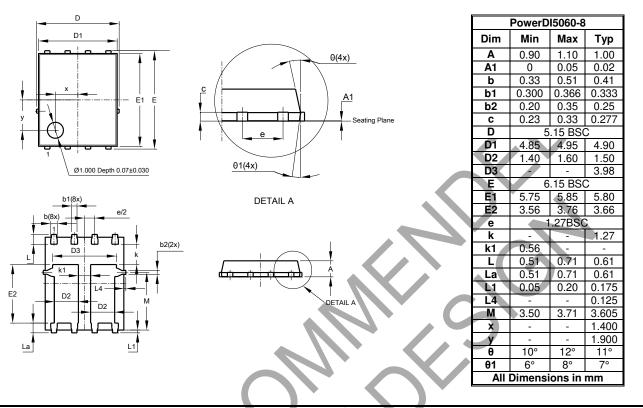






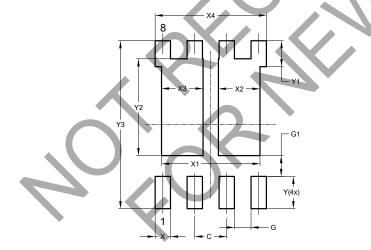
Package Outline Dimensions

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for latest version.



Dimensions	Value
Dimensions	(in mm)
С	1.270
G	0.660
G1	0.820
Х	0.610
X1	3.910
X2	1.650
X3	1.650
X4	4.420
Y	1.270
Y1	1.020
Y2	3.810
Y3	6.610



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